

S83	6	313/510 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
S84	21	313/511 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
S85	37	313/512 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
S86	3	"6406462"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 08:55
S87	8	"6074247"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 09:21
S88	46	(power adj1 module) and (insulated adj1 metal adj1 substrate)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 09:40
S89	15	(power adj1 module) and (insulated adj1 metal adj1 substrate) and housing	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 10:53
S90	0	(telecommunications adj1 hub) and connectors and coaxial and cable	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 10:54
S91	0	(telecommunications adj1 hub) and connectors and coaxial	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 10:55
S92	5	(telecommunications adj1 hub) and connectors	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 13:34

S93	8	(cellular adj1 phone adj1 housing) and hinge	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 14:56
S94	0	361/737.ccls. and adapt*r	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 14:56
S95	84	361/737.ccls. and adapter	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 15:00
S96	29	S95 and cable	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 14:57
S97	30	361/737.ccls. and adaptor	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 15:02
S98	8	S97 and cable	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/20 15:00

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S63	82	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and filler and chromium and copper	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:01
S64	8	"5814935"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 19:38
S65	25	"5319159"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:19
S66	5	"5559399"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:22
S67	164	(levi adj1 dameon)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:23
S68	589	"361"/\$.ccls. and (gandhi adj1 jayprakash)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:30
S69	836	(gandhi adj1 jayprakash)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:30
S70	226	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and seal\$3 and chromium and copper	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:02
S71	96	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and seal\$3 and chromium and copper and (display adj1 device)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:02
S72	68	361/760 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:55

S73	14	361/751 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:55
S74	28	361/761 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:55
S75	6	361/765 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:55
S76	26	361/767 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:56
S77	10	361/768 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:56
S78	11	361/772 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:57
S79	57	313/504 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:57
S80	5581	313/5046and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
S81	75	313/506 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
S82	38	313/509 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58